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Field Stop Trench IGBT

650 V, 50 A

FGHL50T65MQDT

Field stop 4th generation mid speed IGBT technology copacked with full rated current diode.

Features

- Maximum Junction Temperature: $T_J = 175^{\circ}C$
- Positive Temperature Co-efficient for Easy Parallel Operating
- High Current Capability
- Low Saturation Voltage: $V_{CE(Sat)} = 1.45 \text{ V} (Typ.) @ I_C = 50 \text{ A}$
- 100% of the Parts are Tested for ILM (Note 2)
- Smooth and Optimized Switching
- Tight Parameter Distribution
- RoHS Compliant

Typical Applications

- Solar Inverter
- UPS, ESS
- PFC, Converters

MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Collector to Emitter Voltage	V _{CES}	650	V
Gate to Emitter Voltage Transient Gate to Emitter Voltage	V_{GES}	±20 ±30	V
$ \begin{array}{c} \mbox{Collector Current (Note 1)} & @\ T_C = 25^\circ C \\ & @\ T_C = 100^\circ C \end{array} $	Ι _C	80 50	A
Pulsed Collector Current (Note 2)	I _{LM}	200	А
Pulsed Collector Current (Note 3)	I _{CM}	200	А
Diode Forward Current (Note 1) @ $T_{C =} 25^{\circ}C$ @ $T_{C =} 100^{\circ}C$	lF	60 50	A
Pulsed Diode Maximum Forward Current	I _{FM}	200	А
$ \begin{array}{ll} \mbox{Maximum Power Dissipation} & @\ T_C = 25^\circ C \\ & @\ T_C = 100^\circ C \end{array} $	P _D	268 134	W
Operating Junction and Storage Temperature Range	T _J , T _{STG}	–55 to +175	°C
Maximum Lead Temp. for Soldering Purposes (1/8" from case for 5 s)	ΤL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Value limit by bond wire

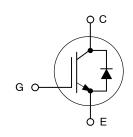
- 2. V_{CC} = 400 V, V_{GE} = 15 V, I_C = 200 A, Inductive Load, 100% tested
- 3. Repetitive rating: pulse width limited by max. junction temperature



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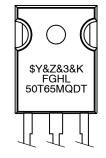
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50 A, 650 V V_{CESat} = 1.45 V





MARKING DIAGRAM



\$Y= ON Semiconductor Logo&Z= Assembly Plant Code&3= 3-Digit Date Code&K= 2-Digit Lot Traceability Code

FGHL50T65MQDT = Specific Device Code

ORDERING INFORMATION

Device	Package	Shipping
FGHL50T65MQDT	TO-247-3L	30 Units / Tube

THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal Resistance Junction-to-case, for IGBT	$R_{ extsf{ heta}JC}$	0.56	°C/W
Thermal Resistance Junction-to-case, for Diode	$R_{ extsf{ heta}JC}$	0.74	°C/W
Thermal Resistance Junction-to-ambient	$R_{ hetaJA}$	40	°C/W

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

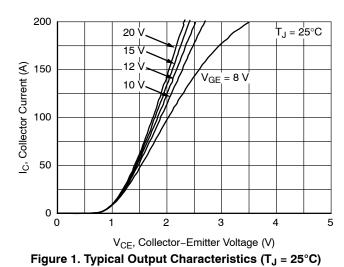
Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS	·					•
Collector to Emitter Breakdown Voltage	V _{GE} = 0 V, I _C = 1 mA	BV _{CES}	650	-	-	V
Temperature Coefficient of Breakdown Voltage	V _{GE} = 0 V, I _C = 1 mA	$\frac{\Delta BV_{CES}}{\Delta T_{J}}$	-	0.6	-	V/°C
Collector-emitter Cut-off Current	V _{GE} = 0 V, V _{CE} = 650 V	I _{CES}	-	-	250	μA
Gate Leakage Current	V _{GE} = 20 V, V _{CE} = 0 V	I _{GES}	-	-	±400	nA
ON CHARACTERISTICS						
Gate to Emitter Threshold Voltage	$V_{GE} = V_{CE}$, $I_C = 50 \text{ mA}$	V _{GE(th)}	3.0	4.5	6.0	V
Collector to Emitter Saturation Voltage	V_{GE} = 15 V, I _C = 50 A, T _J = 25°C V _{GE} = 15 V, I _C = 50 A, T _J = 175°C	V _{CE(sat)}	-	1.45 1.65	1.8 -	V
DYNAMIC CHARACTERISTICS			-			
Input Capacitance	$V_{CE} = 30 V,$	C _{ies}	-	3335	-	pF
Output Capacitance	V _{GE} = 0 V, f = 1 MHz	C _{oes}	-	105	-	
Reverse Transfer Capacitance		C _{res}	-	11	-	
Gate Charge Total	$V_{CE} = 400 V,$	Qg	-	99	-	nC
Gate to Emitter Charge	I _C = 50 A, V _{GE} = 15 V	Q _{ge}	-	17	-	1
Gate to Collector Charge]	Q _{gc}	-	24	-	
SWITCHING CHARACTERISTICS, INDUC	TIVE LOAD					
Turn-on Delay Time	$T_J = 25^{\circ}C,$	t _{d(on)}	-	19	-	ns
Rise Time	V _{CC} = 400 V, I _C = 25 A,	t _r	-	11	-	1
Turn-off Delay Time	R _G = 6 Ω, V _{GE} = 15 V	t _{d(off)}	-	96	-	
Fall Time		t _f	-	58	-	
Turn-on Switching Loss		E _{on}	-	0.47	-	mJ
Turn-off Switching Loss		E _{off}	-	0.29	-]
Total Switching Loss		E _{ts}	_	0.77	-	
Turn-on Delay Time	$T_{J} = 25^{\circ}C,$ $V_{CC} = 400 V,$ $I_{C} = 50 A,$ $R_{G} = 6 \Omega,$ $V_{GE} = 15 V$	t _{d(on)}	_	21	-	ns
Rise Time		t _r	-	30	-	1
Turn-off Delay Time		t _{d(off)}	-	90	-	1
Fall Time		t _f	-	54	-	1
Turn-on Switching Loss	1	E _{on}	-	1.19	-	mJ
Turn-off Switching Loss	1	E _{off}	-	0.63	-	1
Total Switching Loss	1	E _{ts}	_	1.82	-	1

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise noted)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
SWITCHING CHARACTERISTICS, IND	UCTIVE LOAD					
Turn-on Delay Time	$T_{J} = 175^{\circ}C,$	t _{d(on)}	-	18	-	ns
Rise Time	V _{CC} = 400 V, I _C = 25 A,	t _r	-	14	-	1
Turn-off Delay Time	R _G = 6 Ω, V _{GE} = 15 V	t _{d(off)}	-	98	-	1
Fall Time		t _f	-	88	-	1
Turn-on Switching Loss		Eon	-	0.9	-	mJ
Turn-off Switching Loss		E _{off}	-	0.55	-	1
Total Switching Loss		E _{ts}	-	1.44	-	1
Turn-on Delay Time	$T_{J} = 175^{\circ}C,$	t _{d(on)}	-	19	-	ns
Rise Time	V _{CC} = 400 V, I _C = 50 A,	t _r	-	32	-	
Turn-off Delay Time	R _G = 6 Ω, V _{GE} = 15 V	t _{d(off)}	-	99	-	
Fall Time	- GE	t _f	-	82	-	
Turn-on Switching Loss		Eon	-	1.87	-	mJ
Turn-off Switching Loss		E _{off}	-	1.08	-	
Total Switching Loss		E _{ts}	-	2.95	-	
DIODE CHARACTERISTICS						
Diode Forward Voltage	$I_{F} = 50 \text{ A}, \text{ T}_{J} = 25^{\circ}\text{C}$	V _F	-	1.65	2.1	V
	I _F = 50 A, Τ _J = 175°C		-	1.55	-	
DIODE SWITCHING CHARACTERISTIC	CS, INDUCTIVE LOAD					
Reverse Recovery Energy	$T_J = 25^{\circ}C$, $V_{CE} = 400$ V, $I_F = 25$ A,	E _{rec}	-	65	-	μJ
Diode Reverse Recovery Time	di _F /dt = 1000 A/μs	T _{rr}	-	44	-	ns
Diode Reverse Recovery Charge		Q _{rr}	-	387	-	nC
Diode Reverse Recovery Current		I _{rr}	-	18	-	А
Reverse Recovery Energy	$T_J = 25^{\circ}C, V_{CE} = 400 V, I_F = 50 A,$	E _{rec}	-	128	-	μJ
Diode Reverse Recovery Time	di _F /dt = 1000 A/μs	T _{rr}	-	79	-	ns
Diode Reverse Recovery Charge		Q _{rr}	-	681	-	nC
Diode Reverse Recovery Current		I _{rr}	-	17	-	А
Reverse Recovery Energy	$T_J = 175^{\circ}C, V_{CE} = 400 V, I_F = 25 A,$	E _{rec}	-	380	-	μJ
Diode Reverse Recovery Time	di _F /dt = 1000 A/µs	T _{rr}	-	102	-	ns
Diode Reverse Recovery Charge		Q _{rr}	-	1482	-	nC
Diode Reverse Recovery Current		I _{rr}	-	29	-	А
Reverse Recovery Energy	$T_J = 175^{\circ}C, V_{CE} = 400 V, I_F = 50 A,$	E _{rec}	-	544	-	μJ
Diode Reverse Recovery Time	di _F /dt = 1000 A/μs	T _{rr}	_	135	-	ns
Diode Reverse Recovery Charge		Q _{rr}	-	2023	-	nC
Diode Reverse Recovery Current	7	I _{rr}	_	30	_	Α

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS



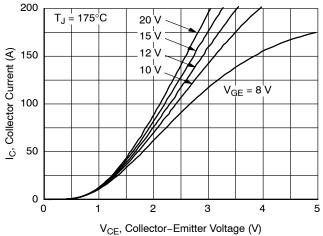


Figure 2. Typical Output Characteristics ($T_J = 175^{\circ}C$)

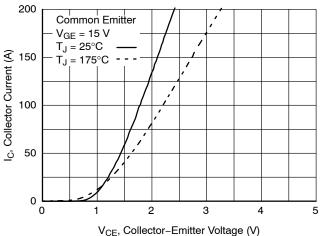


Figure 3. Typical Saturation Voltage Characteristics

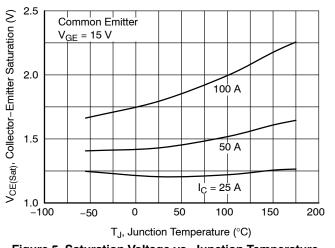


Figure 5. Saturation Voltage vs. Junction Temperature

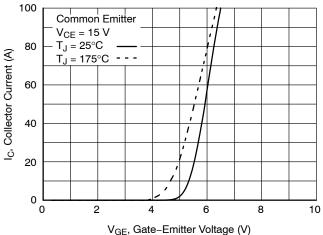
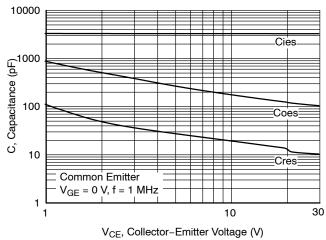
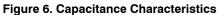
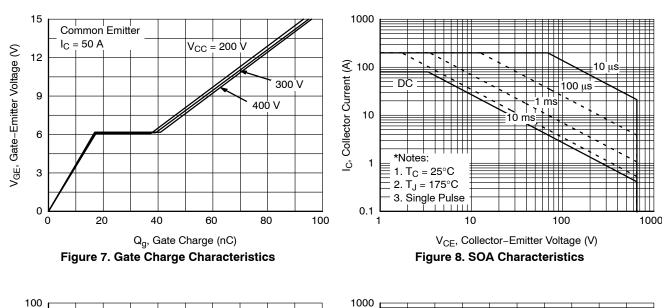


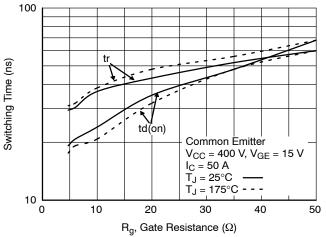
Figure 4. Typical Transfer Characteristics





TYPICAL CHARACTERISTICS (continued)







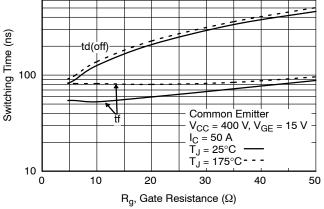


Figure 10. Turn-off Characteristics vs. Gate Resistance

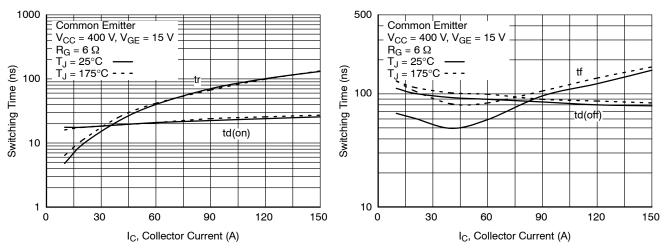
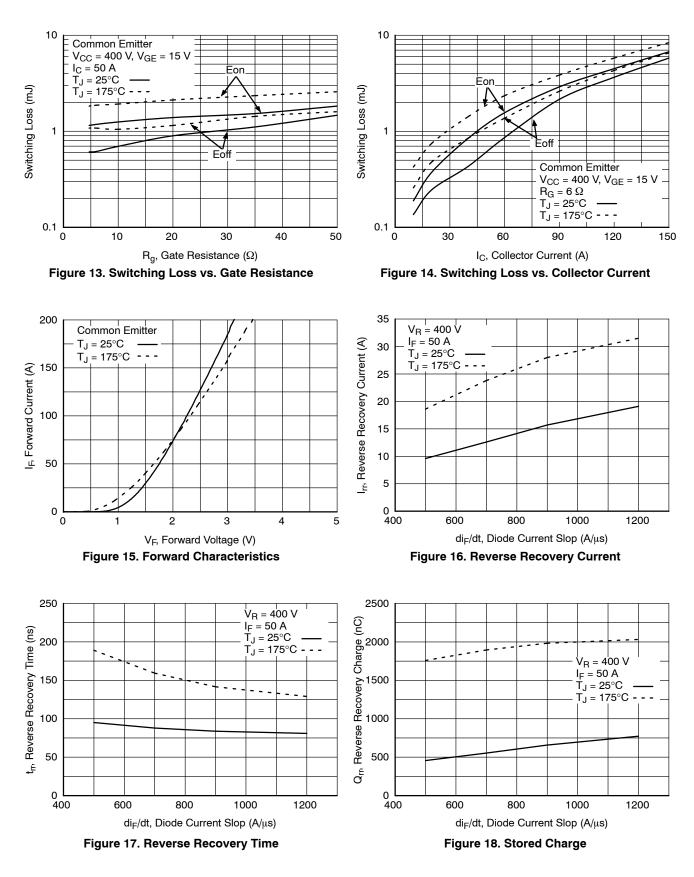


Figure 11. Turn-on Characteristics vs. Collector Current Figure 12. Turn-off Characteristics vs. Collector Current

TYPICAL CHARACTERISTICS (continued)



TYPICAL CHARACTERISTICS (continued)

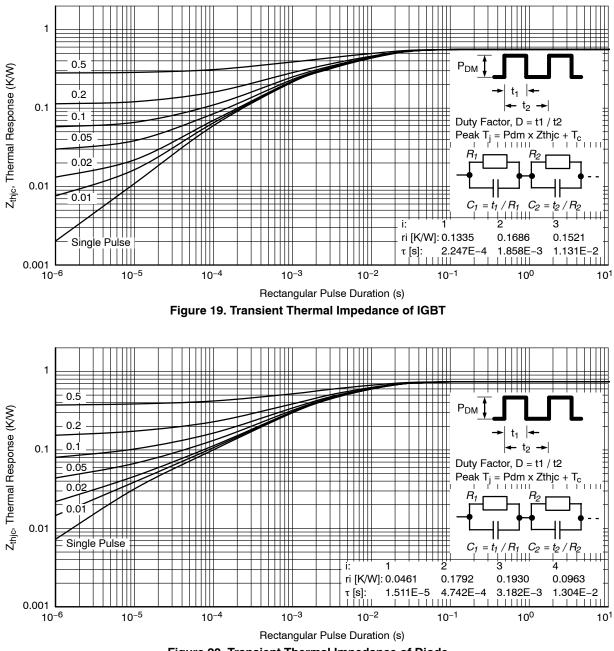
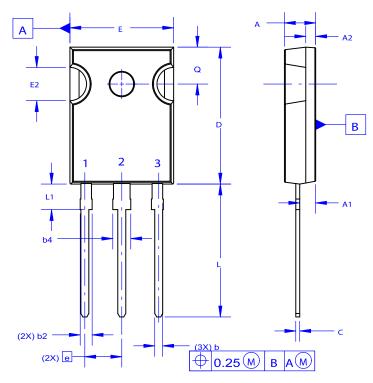


Figure 20. Transient Thermal Impedance of Diode

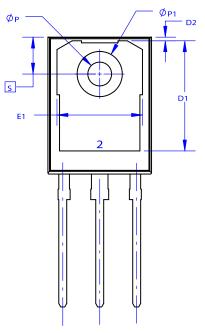
PACKAGE DIMENSIONS





NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD
- FLASH, AND TIE BAR EXTRUSIONS. B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009. D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.



	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	4.58	4.70	4.82	
A1	2.20	2.40	2.60	
A2	1.40	1.50	1.60	
D	20.32	20.57	20.82	
E	15.37	15.62	15.87	
E2	4.96	5.08	5.20	
е	~	5.56	~	
L	19.75	20.00	20.25	
L1	3.69	3.81	3.93	
ØР	3.51	3.58	3.65	
Q	5.34	5.46	5.58	
S	5.34	5.46	5.58	
b	1.17	1.26	1.35	
b2	1.53	1.65	1.77	
b4	2.42	2.54	2.66	
С	0.51	0.61	0.71	
D1	13.08	~	~	
D2	0.51	0.93	1.35	
E1	12.81	~	~	
Ø P 1	6.60	6.80	7.00	

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